



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLE92466ED	Issued	08. April 2022
MA#	MA005429810		
Package	PG-DSO-36-72	Weight*	539.90 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.245	1.53	1.53	15271	15271
leadframe	inorganic material	phosphorus	7723-14-0	0.072	0.01		134	
	non noble metal	iron	7439-89-6	0.241	0.04		447	
	non noble metal	copper	7440-50-8	240.973	44.63	44.68	446327	446908
wire	non noble metal	copper	7440-50-8	3.263	0.60	0.60	6044	6044
encapsulation	organic material	carbon black	1333-86-4	0.824	0.15		1526	
	plastics	epoxy resin	-	32.133	5.95		59517	
	inorganic material	silicondioxide	60676-86-0	241.685	44.78	50.88	447646	508689
leadfinish	non noble metal	tin	7440-31-5	6.656	1.23	1.23	12328	12328
plating	noble metal	silver	7440-22-4	3.599	0.67	0.67	6666	6666
glue	plastics	epoxy resin	-	0.387	0.07		716	
	noble metal	silver	7440-22-4	1.824	0.34	0.41	3378	4094
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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